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| FORM PTO-1449 | | Atty. Docket No.: N19.12-0026 | Serial No.: 09/433,202 |
| <p style="text-align: center;">LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT</p> | | Applicant: | |
| | | Marcheschi et al. | |
| | | Filing Date: | Group Art: |
| | | November 4, 1999 | 1755 |

U. S. PATENT DOCUMENTS

| Examiner Initial | Document No. | Date | Name | Class | Sub Class | Filing Date If Appropriate |
|------------------|--------------|----------|-------------------|-------|-----------|----------------------------|
| AA | 5,064,517 | 11-12-91 | Nobuo Shimo | 204 | 157.51 | |
| AB | 5,318,927 | 07-07-94 | Gurtej S. Sandhu | 437 | 225 | |
| AC | 5,527,423 | 06-18-96 | Neville et al. | 156 | 636 | |
| AD | 4,356,107 | 10-26-82 | Charles C. Payne | 252 | 313 | |
| AE | 4,764,497 | 08-16-88 | Yuasa et al. | 502 | 235 | |
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| AI | 5,246,624 | 09-21-93 | Miller et al. | 252 | 313.2 | |
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| | AK | | | | | | |

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

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| AL | "Fractographic Study of Sinered NanoPhase TiO ₂ " by, Li et al., Material Letter, Vol. 6, No. 7, April 1988, pp. 195-201. |
| AM | "Fabrication of Agglomerate-Free NanoPowders By Hydrothermal Chemical Processing" by, Schmidt et al., Mat. Res. Soc. Symp. Proc. Vol. 520, 1988 <i>no month</i> |

EXAMINER:

DATE CONSIDERED: 9/22/02

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.